You should delete the nylon screws/standoffs and/or the bumpens as needed for your design (or substitute other parts from Hardware.IntLib). Bumper are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.

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Assembly Note

ZZ1

Assembled on PCB labels only.

Assembly Note

ZZ2

These assemblies are ESD sensitive. ESD precautions shall be observed.

Assembly Note

ZZ3

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Assembly Note

ZZ4

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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